

Excellent Integrated System Limited

Stocking Distributor

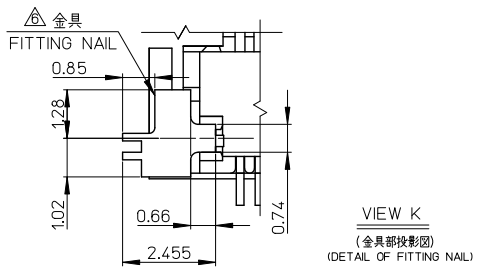
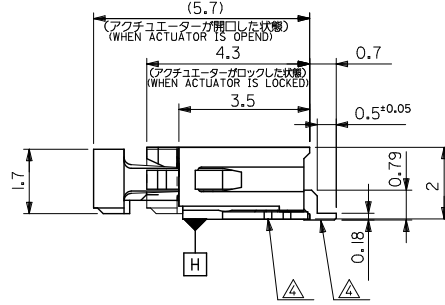
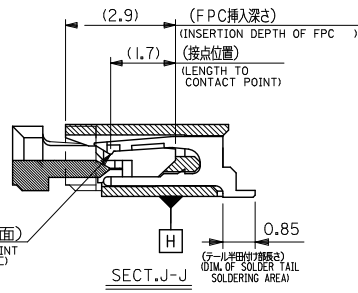
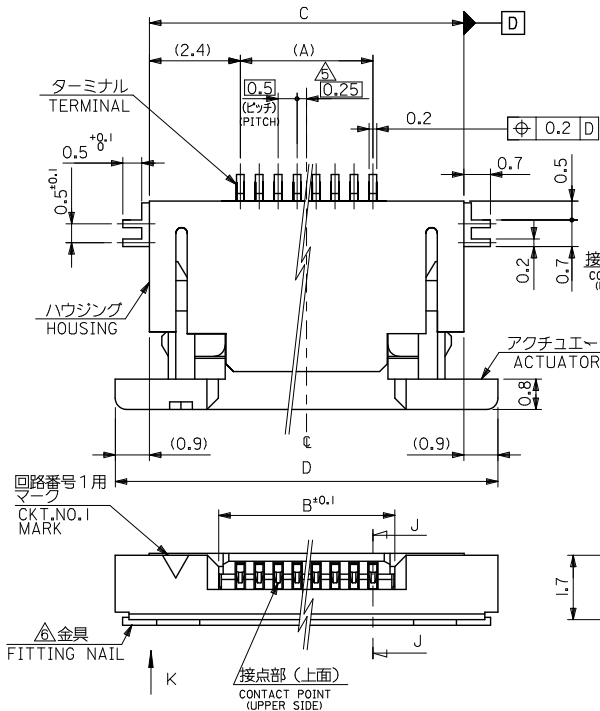
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[52745-1790](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

FOR LIMITED USE BY COMPAL ELECTRONICS, INC.



注記 NOTES

1. 材質: MATERIAL
 ハウジング: 46ナイロン, ガラス充填, UL94V-0, 白色
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
 アクチュエータ: PPS, ガラス充填, UL94V-0, 黒
 ACTUATOR: PPS, GLASS FILLED, UL94V-0, BLACK
 ターミナル: リン青銅 (t=0.2)
 TERMINAL: PHOSPHOR BRONZE (t=0.2)
 金具: リン青銅 (t=0.2)
 FITTING NAIL: PHOSPHOR BRONZE (t=0.2)
 ターミナル: TERMINAL
 接点部: 金メッキ 0.1μm以上
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM
 テール部: 金メッキ 0.05μm以上
 TAIL AREA: GOLD 0.05 MICROMETER MINIMUM
 下地めっき: ニッケル 1.0μm以上
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
 金具: FITTING NAIL
 無光沢めっき 1.0μm以上
 PLATING MATTE TIN 1.0 MICROMETER MINIMUM
 下地めっき: ニッケル 1.0μm以上
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
2. めっき仕様: PLATING
 ターミナル: TERMINAL
 接点部: 金メッキ 0.1μm以上
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM
 テール部: 金メッキ 0.05μm以上
 TAIL AREA: GOLD 0.05 MICROMETER MINIMUM
 下地めっき: ニッケル 1.0μm以上
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
 金具: FITTING NAIL
 無光沢めっき 1.0μm以上
 PLATING MATTE TIN 1.0 MICROMETER MINIMUM
 下地めっき: ニッケル 1.0μm以上
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
3. エンボスステップ梱包時は、アクチュエーターがロックした状態になります。
 IN THE PACKAGE, ACTUATOR OF PART NO.52745-***59 SHOULD BE LOCKED.
 ソルダール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H, UPPER DIRECTION: 0.1 MAXIMUM, LOWER DIRECTION: 0.15 MAXIMUM
4. 偶数極に適用
 APPLY FOR EVEN CIRCUIT.
5. ハタチン剥離止め金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
 R0.3は、FPCの胴体部にかからないこと
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
6. ELV 及び RoHS 適合品
 ELV AND RoHS COMPLIANT

| | | | | | |
|------------------------------------|------|-------|-----|------------------|------|
| 16.1 | 14.3 | 10.65 | 9.5 | 52745-2090 | 20 |
| D | C | B | (A) | EMBOSSED PACKAGE | 極数 |
| CONNECTOR SERIES NO. : 52745-***17 | | | | | 極数 |
| ORDER No. オーダー番号 | | | | | CKT. |

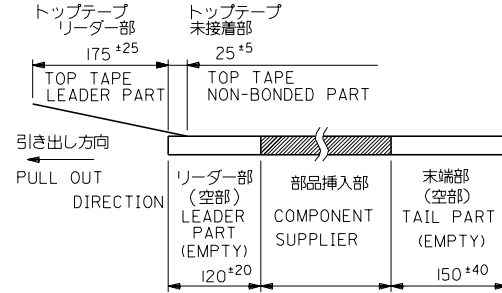
| | | | | | | | | | | |
|---|---------------------------------------|--|----------------------------|---------------------------|---|---------------------|------------------------|---|------------------------|--|
| RELEASED IEC NO. J2011-1160 DRAWN BY DRUNKIYAHARA 2011/03/11 CHIKOKITAKAHASHI 2011/03/16 APPROVED BY KMORIKAWA 2011/03/22 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 10:1 | | DESIGN UNITS METRIC | | THIRD ANGLE PROJECTION | |
| | 10 UNDER | ± 0.2 | DRAWN BY KMIYAHARA | DATE 2011/03/11 | TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING | | | | | |
| | 10 OVER 30 UNDER | ± 0.25 | CHECKED BY KMIYAHARA | DATE 2011/03/16 | MOLEX INCORPORATED | | | | | |
| | 30 OVER | ± 0.3 | APPROVED BY KMORIKAWA | DATE 2011/03/22 | DOCUMENT NO. RSD-52745-088 | | | | | |
| ANGULAR ± 3° | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | MATERIAL NO. SEE TABLE | | SHEET NO. 1 OF 2 | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |

注記 NOTES

1. 製品番号 52745-**17 の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面 SD-52745-**17 を参照下さい。
IN THE PACKAGE,ACTUATOR OF PART NO.52745-**17 SHOULD BE LOCKED
RE DETAILED DIMENSIONS,SEE SD-52745-**17

2. 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)

0.1N~0.7N (10.2gf~71.4gf) 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)

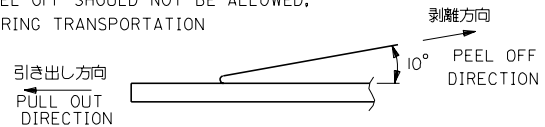
PEELING OFF FORCE OF TOP TAPE

0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)

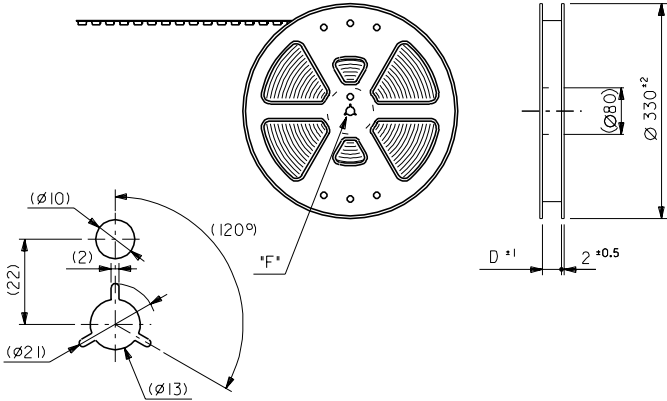
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT

PEEL OFF SHOULD NOT BE ALLOWED,

DURING TRANSPORTATION



引き出し方向
PULL OUT
DIRECTION



DETAIL "F"

5. 材料 キャリアテープ:ポリプロピレン (PP)
トップテープ:PET, PE, PEF
リール:ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

| | | | | | | | |
|-------------------------|-------|--------|------------------------|-------------|---------------------------|-----------------------------|--|
| 角度 ANGLE | | ±30° | | | 材料 MATERIAL | 注記参照 SEE NOTES | MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社 REVISE ONLY ON CAD SYSTEM TITLE 名称 0.5 FPC Conn ZIF SMT RA Upper Contact Embstp Pkg DWG. NO. (SHEET 1 OF 3) REV SD-52745-**90 B |
| 30以上 OVER | ±0.5 | B | 変更 REVISD (J40230) | 00/02/20 | 仕上げ FINISH | — | |
| 10以上 OVER 30未満 UNDER | ±0.25 | A | 変更 REVISD (J40949) | 94/11/17 | 適用電線範囲 WIRE RANGE | — | |
| 10未満 UNDER | ±0.2 | O | 新規作成 RELEASED (J40230) | 94/3/24 | 被覆外径 INS. RANGE | — | |
| 一般公差 GENERAL TOLERANCES | | 記号 LTR | 変更内容 REVISION RECORD | DR/CHK DATE | DRAWN BY 94/3/24 S.AIHARA | CHK'D BY 00/02/20 S.KUNISHI | |

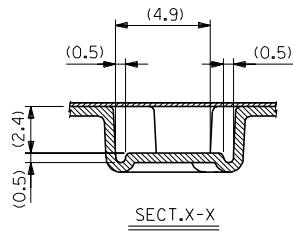
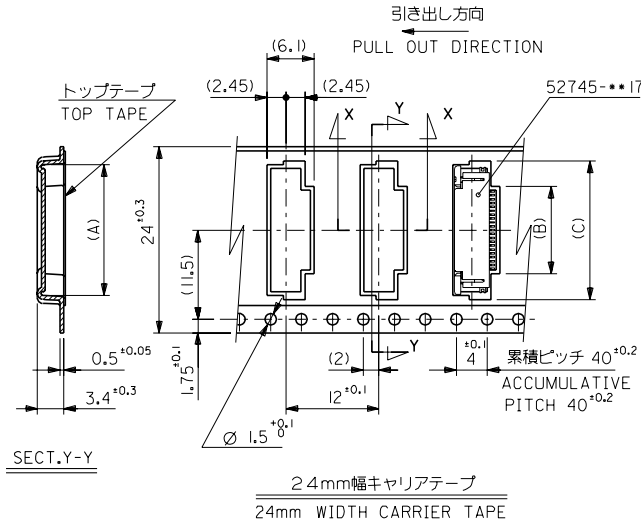
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本図面は日本モレックス(株)の所有する情報を含むもので 当社の許可なく複製を禁止する。 EN-01C(032)MXJ-32

DWG. NO. SD-52745-**90
DIMENSIONS IN METRIC DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1

DWG. NO. SD-52745-**-90

DIMENSIONS IN METRIC DO NOT SCALE DRAWING



| | | | | | | |
|--------------------------------|------|------|------------|------|------------|---------------|
| 24 | 25.5 | 17.4 | 10.8 | 16.4 | 52745-2090 | 20 |
| | | 16.9 | 10.3 | 15.9 | -1990 | 19 |
| | | 16.4 | 9.8 | 15.4 | -1890 | 18 |
| | | 15.9 | 9.3 | 14.9 | -1790 | 17 |
| | | 15.4 | 8.8 | 14.4 | -1690 | 16 |
| | | 14.9 | 8.3 | 13.9 | -1590 | 15 |
| | | 14.4 | 7.8 | 13.4 | -1490 | 14 |
| | | 13.9 | 7.3 | 12.9 | -1390 | 13 |
| | | 13.4 | 6.8 | 12.4 | -1290 | 12 |
| | | 12.9 | 6.3 | 11.9 | -1190 | 11 |
| | | 12.4 | 5.8 | 11.4 | -1090 | 10 |
| | | 11.9 | 5.3 | 10.9 | -0990 | 9 |
| 11.4 | 4.8 | 10.4 | -0890 | 8 | | |
| 10.9 | 4.3 | 9.9 | -0790 | 7 | | |
| 10.4 | 3.8 | 9.4 | 52745-0690 | 6 | | |
| キャリアテープ幅 CARRIER TAPE WIDTH | | D | (C) | (B) | (A) | ENG. NO. |
| | | | | | | 極数 CIRCUIT |

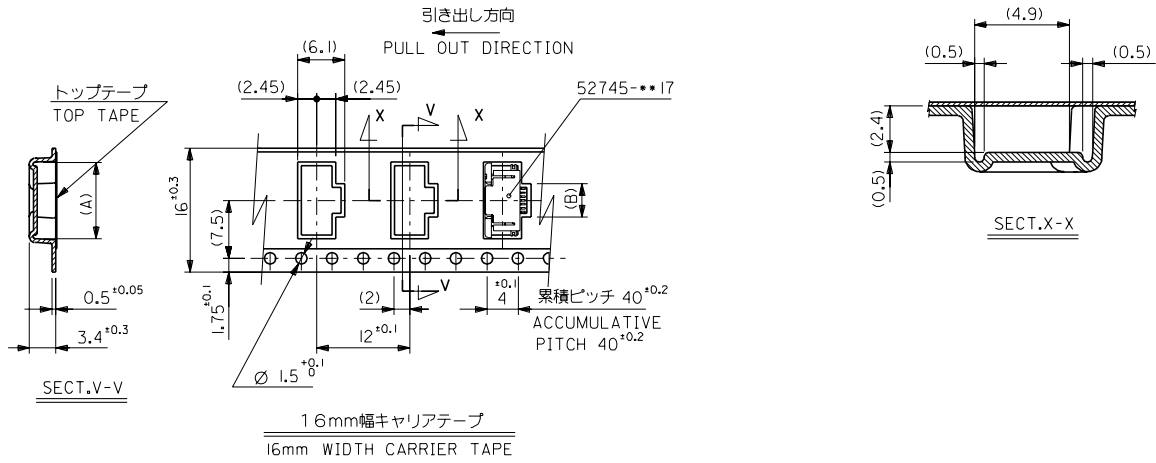
| | | | | | |
|-------------------------|-------|--------|------------------------|----------|---------|
| 角度 ANGLE | ±3° | | | | |
| 30以上 OVER | ±0.5 | B | 変更 REVISD (J4200+0425) | 00/12/20 | |
| 10以上 30未満 UNDER | ±0.25 | A | 変更 REVISD (J40949) | 94/11/17 | |
| 10未満 UNDER | ±0.2 | O | 新規作成 RELEASED (J40230) | 94/3/24 | |
| 一般公差 GENERAL TOLERANCES | | 記号 LTR | 変更内容 REVISION RECORD | DR/CHK | 日付 DATE |

| | |
|---------------------------------------|------------------------------|
| 材料 MATERIAL | |
| SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3 | |
| 仕上げ FINISH | -- |
| 適用電線範囲 WIRE RANGE | -- |
| 被覆外径 INS. RANGE | -- |
| DRAWN BY 94/3/24 S. AIHARA | CHK'D BY 00/12/20 S. KUNISHI |
| APP'D BY 00/12/20 尺取 M. FUKUSHIMA | 尺度 SCALE -- |

| |
|--|
| MOLEX JAPAN CO., LTD. 日本モレックス株式会社 |
| REVISE ONLY ON CAD SYSTEM |
| TITLE 名称 0.5 FPC Conn ZIF SMT RA Upper Contact Embstp Pkg |
| DWG. NO. (SHEET 2 OF 3) REV SD-52745-**-90 B |

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4 3 2 1 EN-01C(032)MXJ-32

DWG. NO. SD-52745-**-90
E
D
C
B
A
DIMENSIONS IN METRIC DO NOT SCALE DRAWING



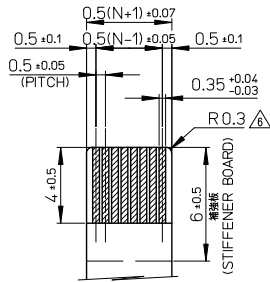
| | | | | | |
|--------------------------------|------|-----|-----|------------|---------------|
| 16 | 17.5 | 2.8 | 8.4 | 52745-0490 | 4 |
| キャリアテープ幅 CARRIER TAPE WIDTH | D | (B) | (A) | ENG. NO. | 極数 CIRCUIT |

| | | | |
|----------------------------------|--|--|--|
| 材料 MATERIAL | SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3 | | MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社 |
| 仕上げ FINISH | --- | | |
| 適用電線範囲 WIRE RANGE | --- | | REVISE ONLY ON CAD SYSTEM |
| 被覆外径 INS. RANGE | --- | | TITLE 名称 0.5 FPC Conn ZIF SMT RA Upper Contact Embstp Pkg |
| DRAWN BY 94/3/24 S.AIHARA | CHK'D BY 00/12/20 S.KUNISHI | | DWG. NO. (SHEET 3 OF 3) REV SD-52745-**-90 |
| APP'D BY 00/12/20 M.FUKUSHIMA | 尺度 SCALE | | B |

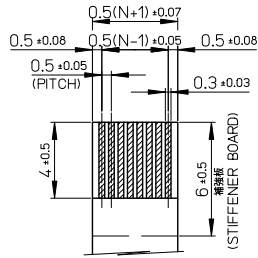
| | | | |
|----------------------------|-----------|-------------------------------|------------|
| 角度 ANGLE | ±30° | | |
| 30以上 OVER | ±0.5 | B 変更 REVISED (J42001-0425) | 00/12/20 |
| 10以上 30未満 UNDER | ±0.25 | A 変更 REVISED (J40949) | 94/11/17 |
| 10未満 UNDER | ±0.2 | O 新規作成 RELEASED (J40230) | 94/3/24 |
| 一般公差 GENERAL TOLERANCES | 記号 LTR | 変更内容 REVISION RECORD | 日付 DATE |

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EN-01C(032)MXJ-32

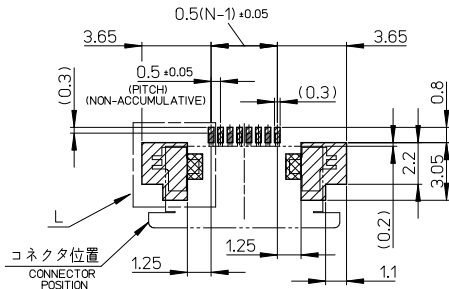
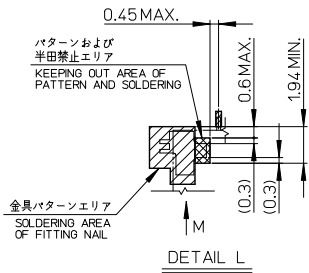
10 9 8 7 6 5 4 3 2 1



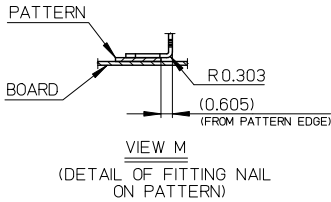
適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3±0.03/-0.03



適合金めっきFPC推奨寸法
APPLICABLE FFC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3±0.03/-0.03



参考基板レイアウト
(マウント面)
RECOMMENDED P.C.B. BOARD
PATTERN DIMENSION(REF.)
(MOUNTING SIDE)



VIEW M
(DETAIL OF FITTING NAIL
ON PATTERN)

注記NOTES

1.使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
ターミナル: リン青銅、銅下地半田めっき (t=0.2)
TERMINAL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING
金具: リン青銅、銅下地半田めっき (t=0.2)
FITTING NAIL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING

2.エンボスステップ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART
NO.52745-***17 SHOULD BE LOCKED.

③ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、
基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM
DATUM-H.

UPPER DIRECTION: 0.1 MAXIMUM
LOWER DIRECTION: 0.15 MAXIMUM

④ 偶数極に適用
APPLY FOR EVEN CIRCUIT.

⑤ ハ・ターン制動止め金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

⑥ R0.3は、FPCの胴体部にかからないこと
R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

FPCについて:

打抜き方向は導体側から補強板を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

RECOMMENDED MATERIAL: STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING BONDING AGENT

| | | | | | | | |
|---------|------------|--|---|--------------|--|------------------------|--|
| REVISED | 2010/07/08 | GENERAL TOLERANCES (UNLESS SPECIFIED) | DIMENSION STYLE | SCALE | DESIGN UNITS | THIRD ANGLE PROJECTION | |
| | 2010/07/08 | ± --- | MM ONLY | 5:1 | METRIC | | |
| | 2010/07/16 | 10 UNDER ± --- | DRAWN BY | DATE | TITLE | | |
| | 2010/07/16 | 10 OVER 30 UNDER ± --- | SAIHARA | 1994/03/24 | 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING | | |
| | | 30 OVER ± --- | CHECKED BY | DATE | | | |
| | | ANGULAR ±3 ° | SKUNISHI | 2000/06/30 | | | |
| | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | APPROVED BY | DATE | | | |
| | | | KNORIKAWA | 2010/07/16 | | | |
| | | | MATERIAL NO. | DOCUMENT NO. | | | |
| | | | SEE TABLE | | | | |
| | | | SIZE | | | | |
| | | | A3 | | | | |
| | | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |